



May 2014

FQA6N90C_F109

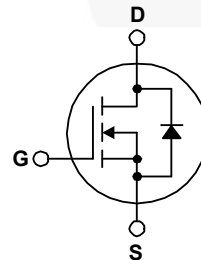
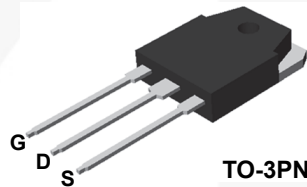
N-Channel QFET[®] MOSFET 900 V, 6 A, 2.3 Ω

Features

- 6 A, 900 V, $R_{DS(on)} = 2.3 \Omega$ (Max.) @ $V_{GS} = 10 V$, $I_D = 3 A$
- Low Gate Charge (Typ. 30 nC)
- Low Crss (Typ. 11 pF)
- 100% Avalanche Tested
- RoHS Compliant

Description

This N-Channel enhancement mode power MOSFET is produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, active power factor correction (PFC), and electronic lamp ballasts.



Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter	FQA6N90C_F109	Unit
V _{DSS}	Drain-Source Voltage	900	V
I _D	Drain Current - Continuous (T _C = 25°C) - Continuous (T _C = 100°C)	6.0	A
		3.87	A
I _{DM}	Drain Current - Pulsed (Note 1)	24.0	A
V _{GSS}	Gate-Source Voltage	± 30	V
E _{AS}	Single Pulsed Avalanche Energy (Note 2)	650	mJ
I _{AR}	Avalanche Current (Note 1)	6.0	A
E _{AR}	Repetitive Avalanche Energy (Note 1)	19.8	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	4.0	V/ns
P _D	Power Dissipation (T _C = 25°C)	198	W
	- Derate above 25°C	1.59	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to +150	°C
T _L	Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	300	°C

Thermal Characteristics

Symbol	Parameter	FQA6N90C_F109	Unit
R _{θJC}	Thermal Resistance, Junction-to-Case, Max.	0.63	°C/W
R _{θCS}	Thermal Resistance, Case-to-Sink, Typ.	0.24	°C/W
R _{θJA}	Thermal Resistance, Junction-to-Ambient, Max	40	°C/W

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FQA6N90C_F109	FQA6N90C	TO-3PN	Tube	N/A	N/A	30 units

Electrical Characteristics T_C = 25°C unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit	
Off Characteristics							
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0 V, I _D = 250 μA	900	--	--	V	
ΔBV _{DSS} /ΔT _J	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C	--	1.07	--	V/°C	
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 900 V, V _{GS} = 0 V	--	--	10	μA	
		V _{DS} = 720 V, T _C = 125°C	--	--	100	μA	
I _{GSSF}	Gate-Body Leakage Current, Forward	V _{GS} = 30 V, V _{DS} = 0 V	--	--	100	nA	
I _{GSSR}	Gate-Body Leakage Current, Reverse	V _{GS} = -30 V, V _{DS} = 0 V	--	--	-100	nA	
On Characteristics							
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250 μA	3.0	--	5.0	V	
R _{DS(on)}	Static Drain-Source On-Resistance	V _{GS} = 10 V, I _D = 3.0 A	--	1.93	2.3	Ω	
g _{FS}	Forward Transconductance	V _{DS} = 50 V, I _D = 3.0 A	--	5.5	--	S	
Dynamic Characteristics							
C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V, f = 1.0 MHz	--	1360	1770	pF	
C _{oss}	Output Capacitance		--	110	145	pF	
C _{rss}	Reverse Transfer Capacitance		--	11	15	pF	
Switching Characteristics							
t _{d(on)}	Turn-On Delay Time	V _{DD} = 450 V, I _D = 6.0A, R _G = 25 Ω	--	35	80	ns	
t _r	Turn-On Rise Time		--	90	190	ns	
t _{d(off)}	Turn-Off Delay Time		(Note 4)	--	55	120	ns
t _f	Turn-Off Fall Time		(Note 4)	--	60	130	ns
Q _g	Total Gate Charge	V _{DS} = 720 V, I _D = 6.0A, V _{GS} = 10 V	--	30	40	nC	
Q _{gs}	Gate-Source Charge		(Note 4)	--	9.0	--	nC
Q _{gd}	Gate-Drain Charge		(Note 4)	--	12	--	nC
Drain-Source Diode Characteristics and Maximum Ratings							
I _S	Maximum Continuous Drain-Source Diode Forward Current		--	--	6.0	A	
I _{SM}	Maximum Pulsed Drain-Source Diode Forward Current		--	--	24	A	
V _{SD}	Drain-Source Diode Forward Voltage	V _{GS} = 0 V, I _S = 6.0 A	--	--	1.4	V	
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _S = 6.0 A, di _F / dt = 100 A/μs	--	630	--	ns	
Q _{rr}	Reverse Recovery Charge		--	6.9	--	μC	

NOTES:

1. Repetitive rating: pulse-width limited by maximum junction temperature.
2. L = 34 mH, I_{AS} = 6 A, V_{DD} = 50 V, R_G = 25 Ω, starting T_J = 25°C.
3. I_{SD} ≤ 6 A, di/dt ≤ 200 A/μs, V_{DD} ≤ BV_{DSS}, starting T_J = 25°C.
4. Essentially independent of operating temperature typical characteristics.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

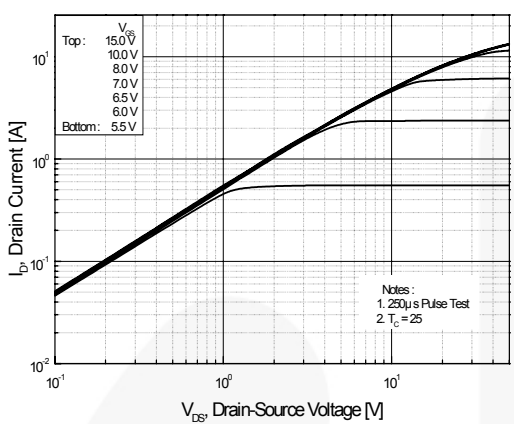


Figure 2. Transfer Characteristics

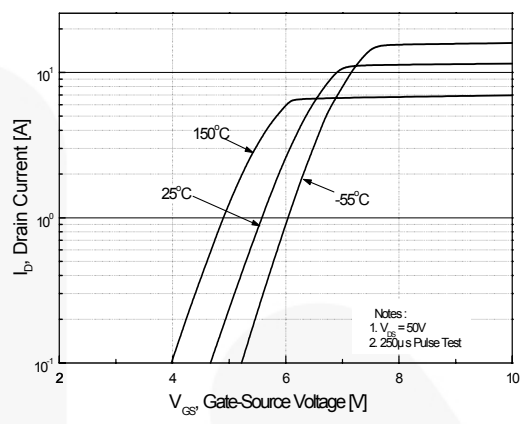


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

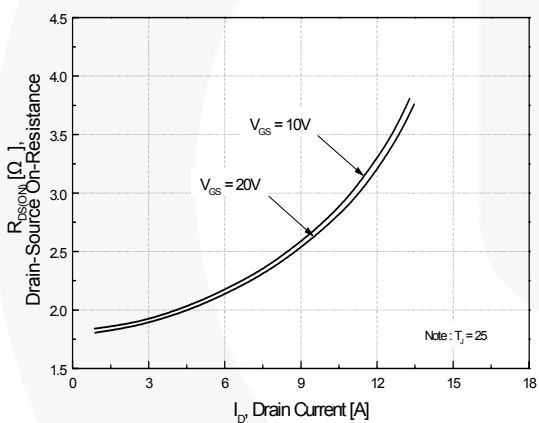


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

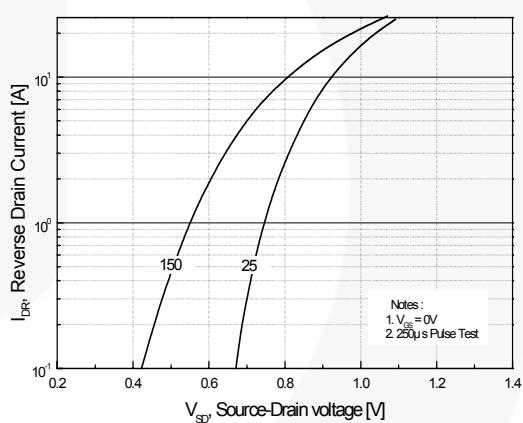


Figure 5. Capacitance Characteristics

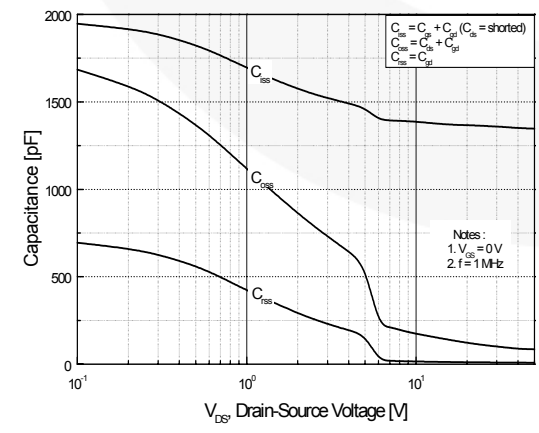
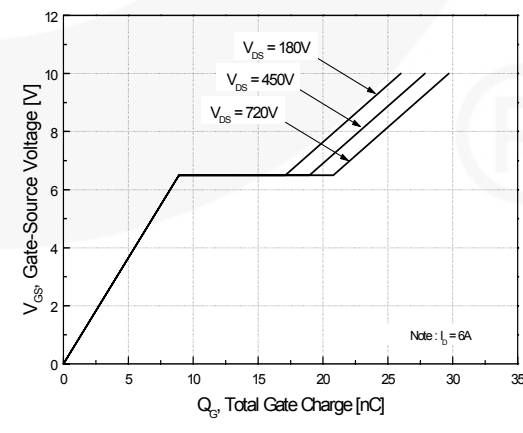


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

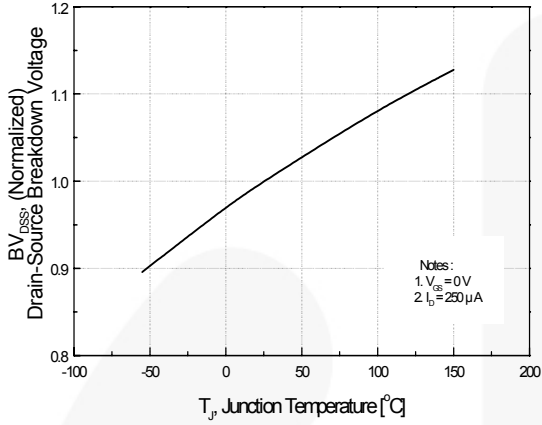


Figure 8. On-Resistance Variation vs. Temperature

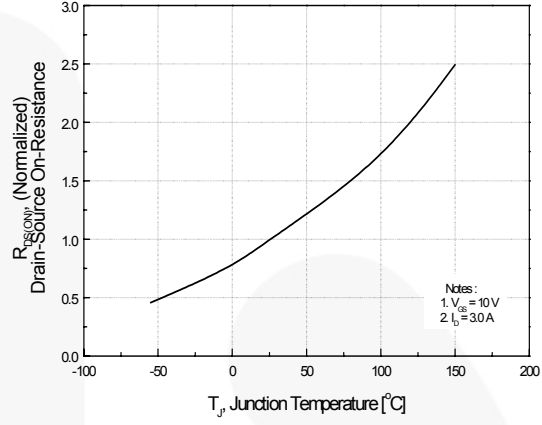


Figure 9. Maximum Safe Operating Area

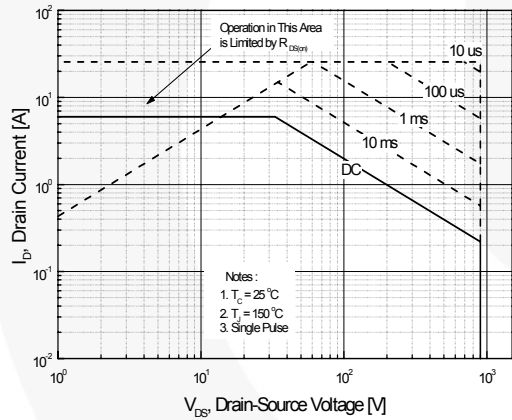


Figure 10. Maximum Drain Current vs. Case Temperature

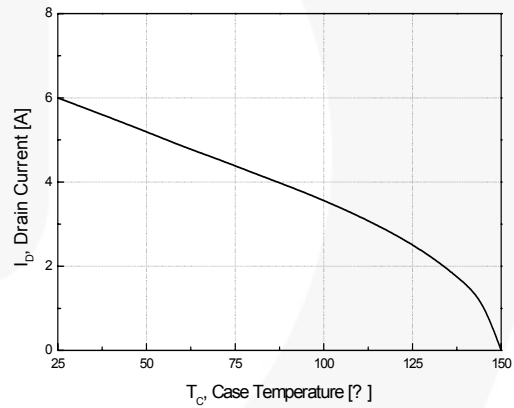
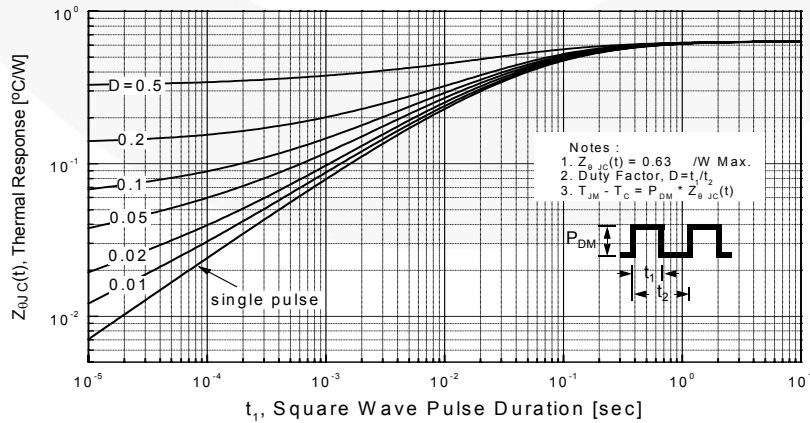


Figure 11. Transient Thermal Response Curve



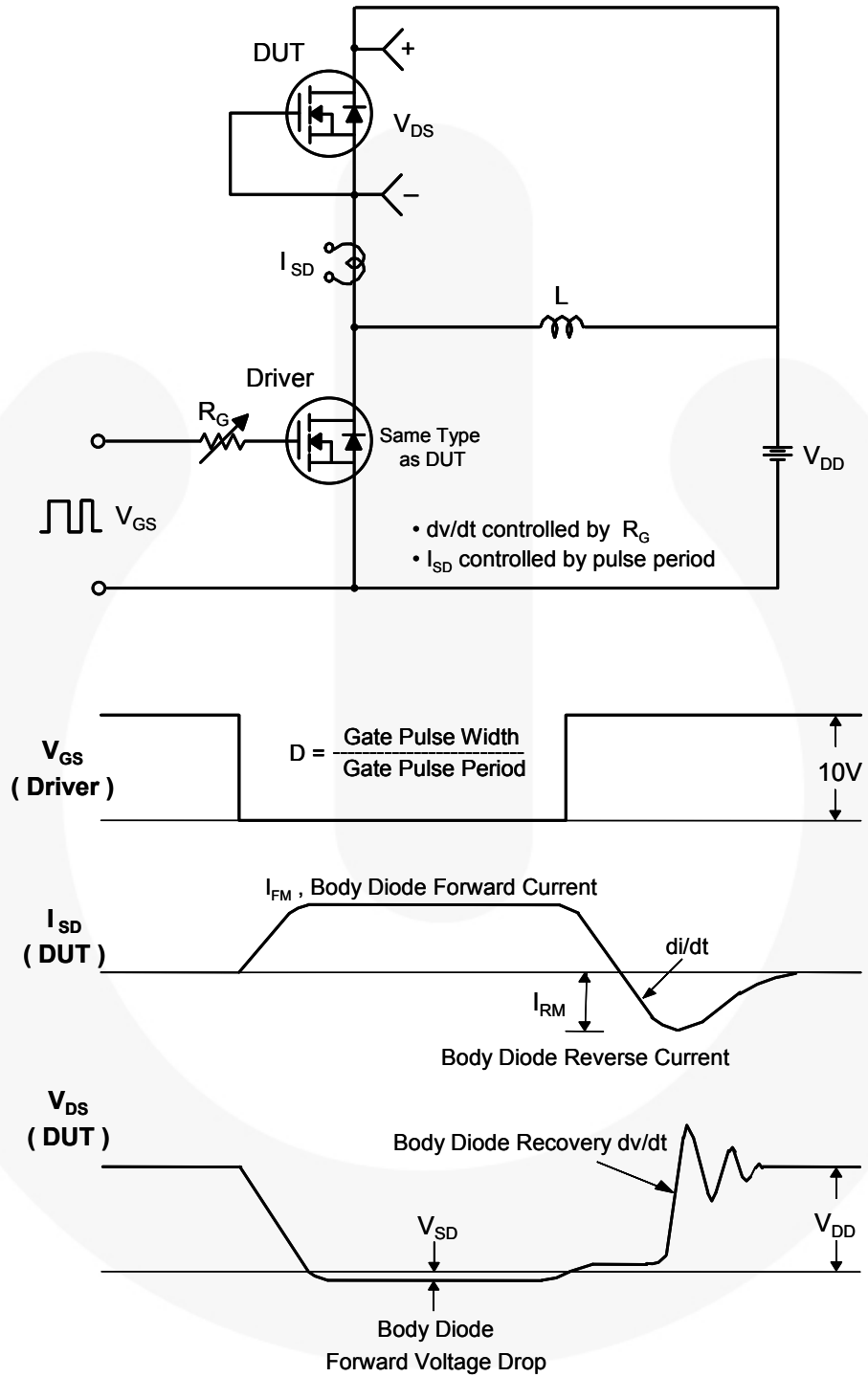
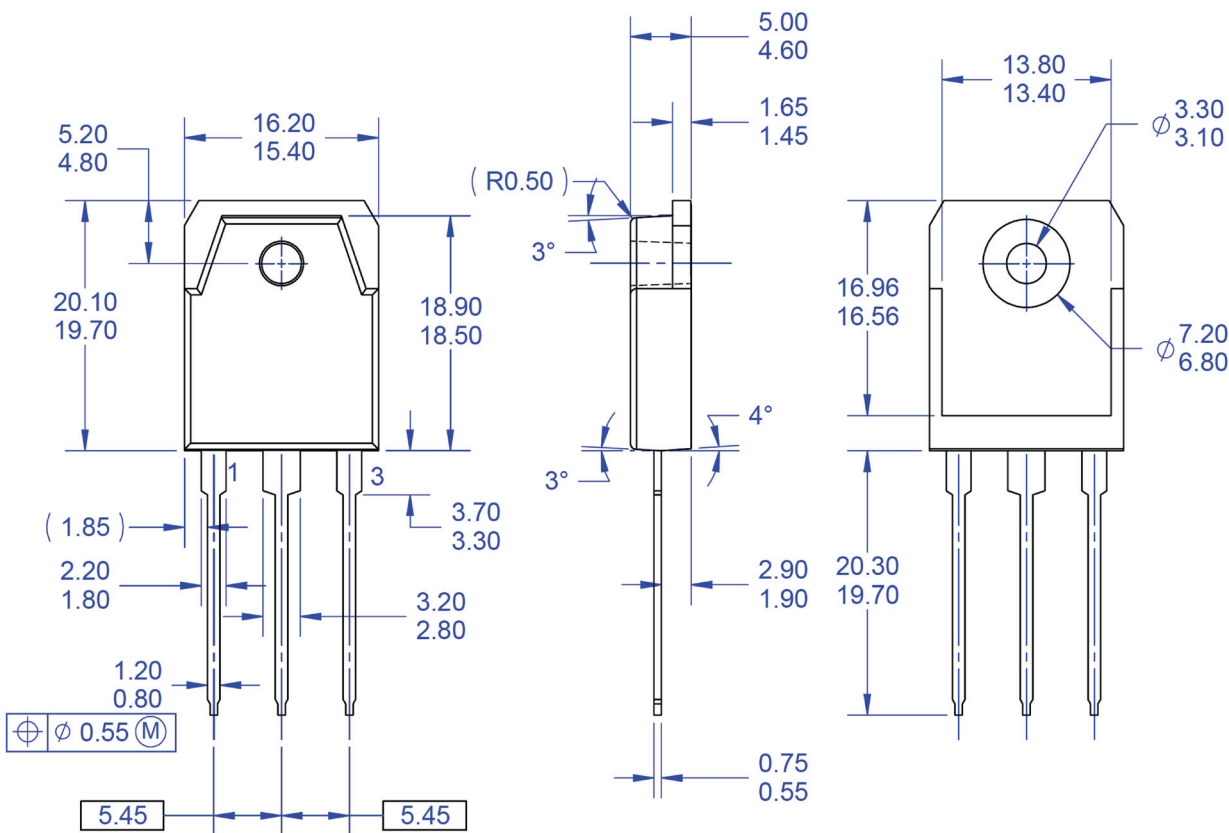


Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

Mechanical Dimensions



NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE CONFORMS TO EIAJ SC-65 PACKAGING STANDARD.
- B) ALL DIMENSIONS ARE IN MILLIMETERS.
- C) DIMENSION AND TOLERANCING PER ASME14.5-2009.
- D) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- E) DRAWING FILE NAME: TO3PN03AREV1.
- F) FAIRCHILD SEMICONDUCTOR.

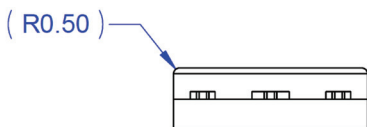


Figure 16. TO3PN, 3-Lead, Plastic, EIAJ SC-65

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